EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	("6333563" or "20040173914" or "6806560" or "66327040").pn.	US-PGPUB; USPAT	OR	ON	2007/03/25 10:41
L15	109	(underfill$3 near5 ("CTE" and (thermal near2 expansion)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 11:08
L16	95	15 and (patial or partially or size or micron or diameter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 11:09
L20	5	((underfill$3 near2 microns)and (filler with particle with(size or diameter or radius or radii)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 11:40
L21	17	("5001542" | "5907190" | "5981313" | "5982631" | "6049038" | "6121689" | "6133639" | "6137183").PN. OR ("6373142").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/25 11:45

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C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10711501 solder interconnect array with optimal mechanical int

L28	50	((underfill$3 or encapsulant or encapsulat$3) with(filler or particale or metal or oxide) with (("32" or "30" or "300") with micron))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/03/25 11:56
L29	180	(underfill$3 with(filler or particle or metal or oxide) with (size or diameter or radius or micron))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/03/25 12:46
L30	17	("5001542" | "5907190" | "5981313" | "5982631" | "6049038" | "6121689" | "6133639" | "6137183"). PN. OR ("6373142"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2007/03/25 12:38
L31	106	((underfill$3 or encapsulant or encapsulat$3)near50 (gap or space) with(filler near100 (size or diameter or radius or radii)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/03/25 13:20
L35	33	("5953814"|"5968670"|"506 0844"|"5784261"|"6333563 "|"6632704"|"6674172"|"68 06560"|"6015722"|"604865 6"|"6177728"|"6294271"|"6 310120"|"6333563"|"65068 69"|"6572980"|"6586846"). PN.	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/03/25 13:38

L36	6	35 and (filler and gap and (solder$3 and ball and size))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 13:44
L42	8	(((underfill$3 or encapsulat$3 or encapsulant) with filler)and gap and (solder$3 same ball same size)same (join$3 or bond$3) same (substrate near5 (circuit near2 board)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:31
L44	4	(((underfill$3 or encapsulat$3 or encapsulant) with filler)and ((gap near100 height) with (("300" or "900") near50 microns)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:04
L45	41	("5088189" | "5128746" | "5136365" | "5349240" | "5376403" | "5587342" | "5629566" | "5710071" | "5729440" | "5742100" | "5751068" | "5770476" | "5801072" | "5801449" | "5861323" | "5985043" | "5985456" | "6077380"). PN. OR ("6335571"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/25 14:08
L47	298	228/215.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32

L48	488	228/178.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32
L49	1091	228/180.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32
L50	991	228/180.21.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32
L51	1297	228/180.22.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32
L52	119	228/244.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32

L53	3924	L47 or L48 or L49 or L50 or L51 or L52	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:32
L56	3	L53 and (((underfill$3 or encapsulat$3 or encapsulant) and filler)and gap and (solder$3 same ball same size)and (join$3 or bond$3) and (substrate same (circuit with board)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/25 14:34